502759489 04/09/2014

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shunpei Yamazaki	04/04/2011

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.	
Street Address:	398, HASE	
City:	ATSUGI-SHI, KANAGAWA-KEN	
State/Country:	JAPAN	
Postal Code:	243-0036	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14184799

CORRESPONDENCE DATA

Fax Number: (877)769-7945

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

Phone: (202) 783-5070 **Email:** apsi@fr.com

Correspondent Name: JOHN F. HAYDEN

Address Line 1: FISH & RICHARDSON P.C.

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ATTORNEY DOCKET NUMBER:	12732-0845003
NAME OF SUBMITTER:	APRIL K. SAUNDERS-FULLER
SIGNATURE:	/April K. Saunders-Fuller/
DATE SIGNED:	04/09/2014

Total Attachments: 1

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PATENT 502759489 REEL: 032632 FRAME: 0288

Attorney Docket No. 12732-0845003 Client Reference No. US13468-D1C1

ASSIGNMENT

For valuable consideration, I, <u>Shunpei YAMAZAKI of Setagaya</u>, <u>Tokyo</u>, <u>Japan</u> hereby assign to <u>Semiconductor Energy Laboratory Co.</u>, <u>Ltd.</u>, a <u>Japanese</u> corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by me this day, entitled METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE, filed February 20, 2014 _____, and assigned U.S. Serial Number 14/184,799, and I authorize and request the Assignee or the attorneys appointed in said application to hereafter complete this assignment by inserting above the filling date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and I agree for myself and my respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature

RECORDED: 04/09/2014

Name:

Date:

Shunpei YAMAZAKI

PATENT

REEL: 032632 FRAME: 0289